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MOSIS: Present and Future

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20. ABSTRACT (Continue on reverse side if necessary and identify by block number) MOSIS is DARPA's MOS Implementation System. For the past three years it has provided packaged parts for over 2,000 VLSI design projects submitted by designers from over 60 organizations. Currently, MOSIS provides 1,300 projects a year in nMOS, CMOS/Bulk and CMOS/SOS technologies and also provides access to PCB fabrication. This paper discusses the services MOSIS currently offers and those that it is preparing to offer.		

